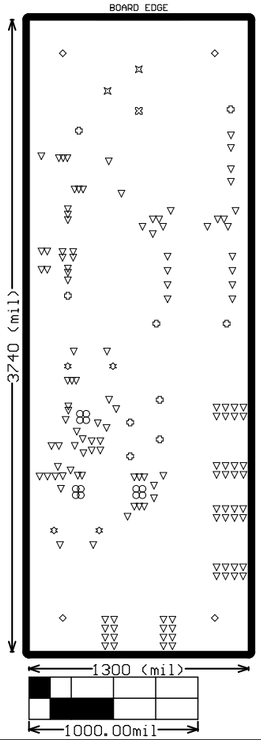
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer L1	Copper	1.40mil		
4	Dielectric1	FR-406	20.00mil	4.6	
5	GND Plane L2	Copper	1.40mil		
6	Dielectric 2	FR-406	15.00mil	4.6	
7	Power Plane L3	Copper	1.40mil		
8	Dielectric 3	FR-406	20.00mil	4.6	
9	Bottom Layer L4	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
◌	4	35.43mil (0.900mm)	NPTH	Round
⌑	12	7.87mil (0.200mm)	PTH	Round
◇	148	10.00mil (0.254mm)	PTH	Round
○	9	63.00mil (1.600mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
▽	2	29.92mil (0.760mm)	PTH	Slot
☼	1	39.76mil (1.010mm)	PTH	Slot
	180 Total			

Single ended tracks 50 ohms Top Layer and Bottom Layer equal 35mils width.

TEXAS INSTRUMENTS

PROJECT TITLE: TrasimpedanceAmplifier_OPA857_THS4541
DESIGNED FOR: Public Release
FILE NAME: TIA_OPA857_THS4541-A.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: 6590370	REV: A	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: TIDA-00725		
PLOT NAME = Fabrication Drawing	GENERATED : 10/14/2016 11:17:43 AM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Samir Cherian	Phung Luong
SCALE: 0.70	ALTIUM DESIGNER VERSION: 16.0.9.368